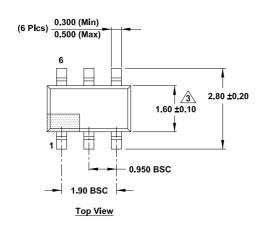
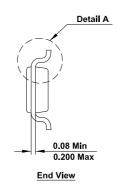
Plastic Packages for Integrated Circuits

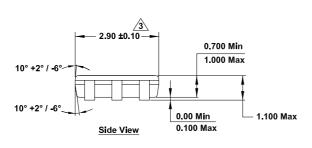
Package Outline Drawing

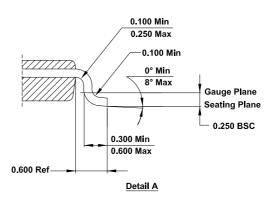
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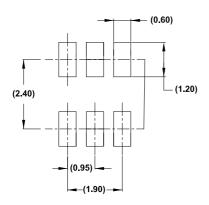
6 Lead Thin Small Outline Transistor (TSOT) Plastic Package Rev 2, 12/20











Typical Recommended Land Pattern

Note

- 1. Dimensioning and tolerancing conform to ASME Y14.5m-1994.
- 2. Die is facing up for mold. Die is facing down for trim/form, that is reverse trim/form.
- $\stackrel{\textstyle \checkmark}{\cancel{3}}$ Dimensions are exclusive of mold flash and gate burr.
- 4. The footlength measuring is based on the gauge plane method.
- 5. All specifications comply to JEDEC Spec MO193 Issue C.